



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Confirmation No.: 4785

Kwun-Yao Ho et al.

Art Unit: 2813

Application No.: 10/734,195

Examiner: Bryant, Deloris S.

Filed: December 15, 2003

Attorney Dkt. No.: 025796-00014

For: HIGH-DENSITY MULTI-CHIP MODULE PACKAGE

RESPONSE UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

June 9, 2006

Sir:

In response to the Official Action dated March 9, 2006. Applicants respectfully request that the Examiner reconsider the application according to the following remarks.

Amendments to the Claims begin on page 2.

Remarks begin on page 4.